

SEMICONDUCTING DEVICE WITH STACKED DICE

Abstract of the Disclosure

Some embodiments of the present invention relate to a semiconducting
5 device and method that include a substrate and a first die that is attached to the
substrate. The first die includes active circuitry (e.g., a flash memory array or logic
circuitry) on an upper surface of the first die. The semiconducting device further
includes a spacer that covers the active circuitry on the upper surface of the first die
and a second die that is stacked onto the spacer and the first die. The spacer extends
10 from a first side of the first die to an opposing second side of the first die. The
spacer also extends near a third side of the first die and an opposing fourth side of
the first die such that the active circuitry is exposed near the third and fourth sides of
the first die.

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